

TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62008AP, TD62008F, TD62008AF

7CH DARLINGTON SINK DRIVER

The TD62008AP / F / AF are high-voltage, high-current darlington drivers comprised of seven NPN darlington pairs.

All units feature integral clamp diodes for switching inductive loads and protective diodes against a negative input voltage.

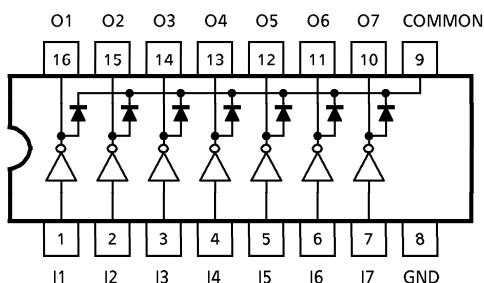
The TD62008AP / F / AF are suitable for interfaces from minus and plus dual supply voltage system to plus single supply voltage system.

Applications include relay, hammer, lamp and display (LED) drivers.

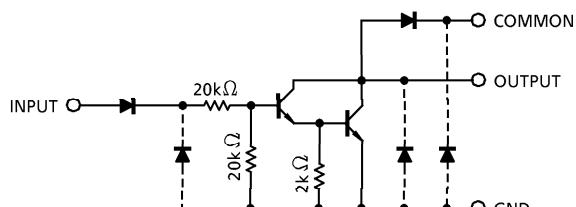
FEATURES

- Output current (single output) 400mA (Max.)
- High sustaining voltage output 50V (Min.)
- Output clamp diodes
- Protective diodes against a negative input voltage
- Inputs base resistor $R_{IN} = 20k\Omega$
- Inputs compatible with 9~15V PMOS, CMOS.
- Package type-AP : DIP-16pin
- Package type-F, AF : SOP-16pin

PIN CONNECTION (TOP VIEW)



SCHEMATICS (EACH DRIVER)



(Note) The input and output parasitic diodes cannot be used as clamp diodes.

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MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Output Sustaining Voltage	AP / AF	V_{CE} (SUS)	- 0.5 ~ 50	V
	F		- 0.5 ~ 35	
Output Current		I_{OUT}	400	mA/ch
Input Voltage		V_{IN}	- 40 ~ 40	V
Clamp Diode Reverse Voltage	AP / AF	V_R	50	V
	F		35	
Clamp Diode Forward Current		I_F	400	mA
Power Dissipation	AP	P_D	1.47	W
	F / AF		0.625 (Note)	
Operating Temperature		T_{opr}	- 40 ~ 85	°C
Storage Temperature		T_{stg}	- 55 ~ 150	°C

(Note) On Glass Epoxy PCB
(30 × 30 × 1.6mm Cu 50%)RECOMMENDED OPERATING CONDITIONS ($T_a = - 40 \sim 85^\circ\text{C}$)

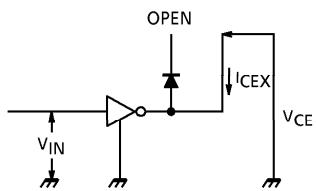
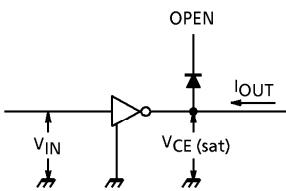
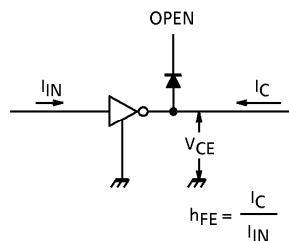
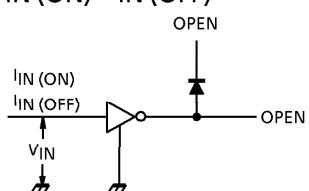
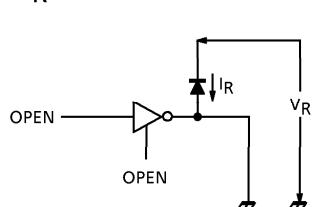
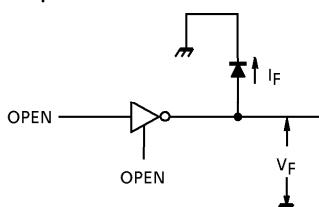
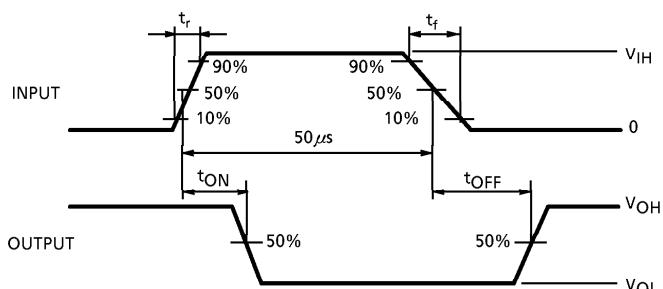
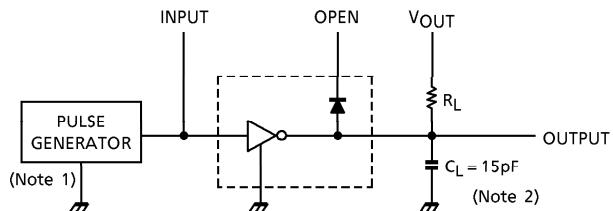
CHARACTERISTIC		SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Output Sustaining Voltage	AP / AF	V_{CE} (SUS)	DC 1 Circuit, $T_{pw} = 25\%$, Duty = 40% $T_{pw} = 25\text{ms}$, Duty = 10%, 7 Circuits	0	—	50	V
	F			0	—	35	
Output Current		I_{OUT}	DC 1 Circuit, $T_{pw} = 25\%$, Duty = 40% $T_{pw} = 25\text{ms}$, Duty = 10%, 7 Circuits	0	—	400	mA
Input Voltage		V_{IN}		0	—	200	
Clamp Diode Reverse Voltage	AP / AF	V_R		—	—	50	V
	F			—	—	35	
Clamp Diode Forward Current		I_F		—	—	400	mA
Power Dissipation	AP	P_D	(Note)	—	—	0.52	W
	F / AF			—	—	0.325	

(Note) On Glass Epoxy PCB (30 × 30 × 1.6mm Cu 50%)

ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC		SYMBOL	TEST CIRCUIT	TEST CONDITION		MIN.	TYP.	MAX.	UNIT	
Output Leakage Current	AP / AF	I_{CEX}	1	$V_{OUT} = 50\text{V}$		—	—	100	μA	
	F			$V_{OUT} = 35\text{V}$		—	—	100		
Collector-Emitter Saturation Voltage		V_{CE} (sat)	2	$I_{OUT} = 400\text{mA}$		—	1.3	2.4	V	
				$I_{OUT} = 200\text{mA}$		—	1.0	1.6		
Input Current	"H" Level	I_{IN} (ON)	4	$V_{IN} = 18\text{V}$		—	0.85	1.8	mA	
	"L" Level	I_{IN} (OFF)		$V_{IN} = 35\text{V}$		—	—	3.8		
DC Current Transfer Ratio		h_{FE}	3	$V_{CE} = 4\text{V}$, $I_{OUT} = 350\text{mA}$		1000	3000	—		
Clamp Diode Reverse Current		I_R	5	$V_R = 50\text{V}$, $V_R = 35\text{V}$ (Type-F)		—	—	100	μA	
Clamp Diode Forward Voltage		V_F	6	$I_F = 400\text{mA}$		—	1.5	2.4	V	
Turn-On Delay	AP / AF	t_{ON}	7	$V_{OUT} = 50\text{V}$, $R_L = 156\Omega$		—	0.1	—	μs	
	F					—	—	—		
Turn-Off Delay	AP / AF	t_{OFF}		$V_{OUT} = 35\text{V}$, $R_L = 110\Omega$		—	0.2	—	μs	
	F					—	—	—		

TEST CIRCUIT

1. I_{CEX} 2. $V_{CE(\text{sat})}$ 3. h_{FE} 4. $I_{IN(\text{ON})}, I_{IN(\text{OFF})}$ 5. I_R 6. V_F 7. t_{ON}, t_{OFF} 

(Note 1) Pulse Width 50μs

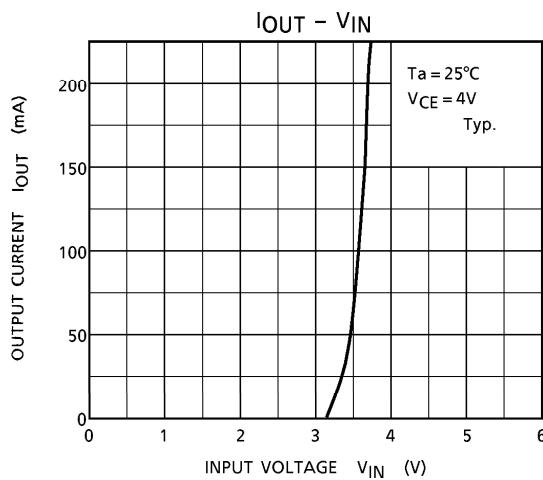
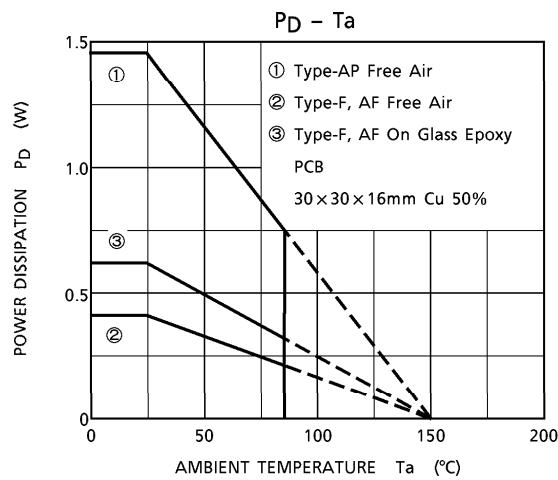
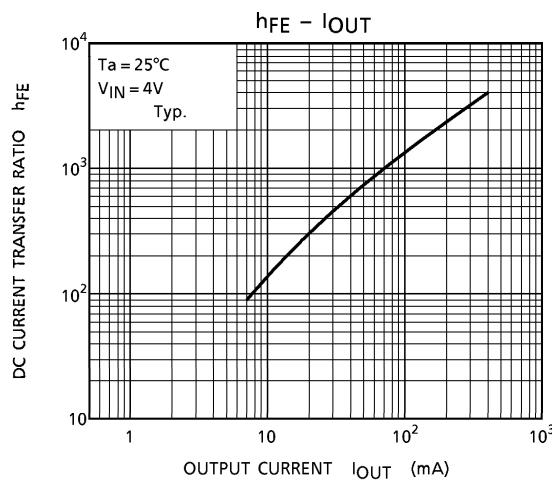
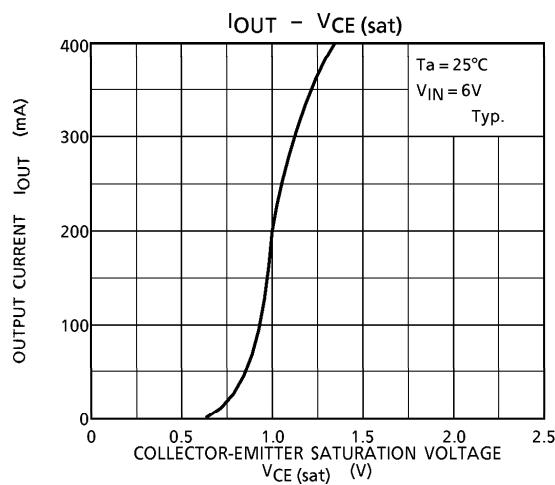
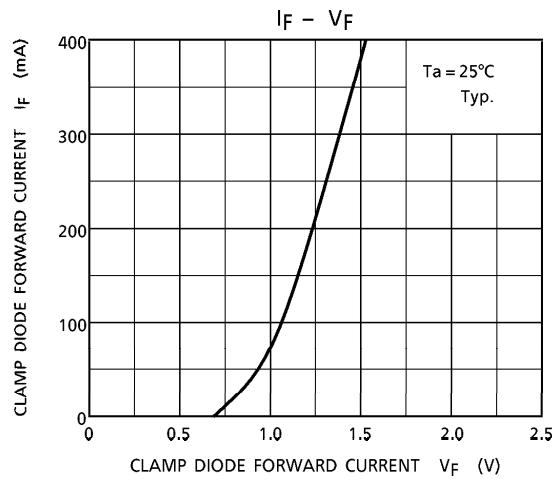
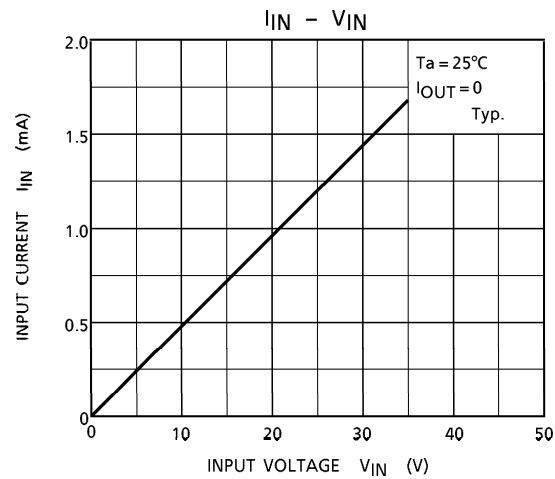
Duty Cycle 10%

Output Impedance 50Ω

 $t_r \leq 5\text{ns}, t_f \leq 10\text{ns}$ (Note 2) C_L includes probe and jig capacitance

PRECAUTIONS for USING

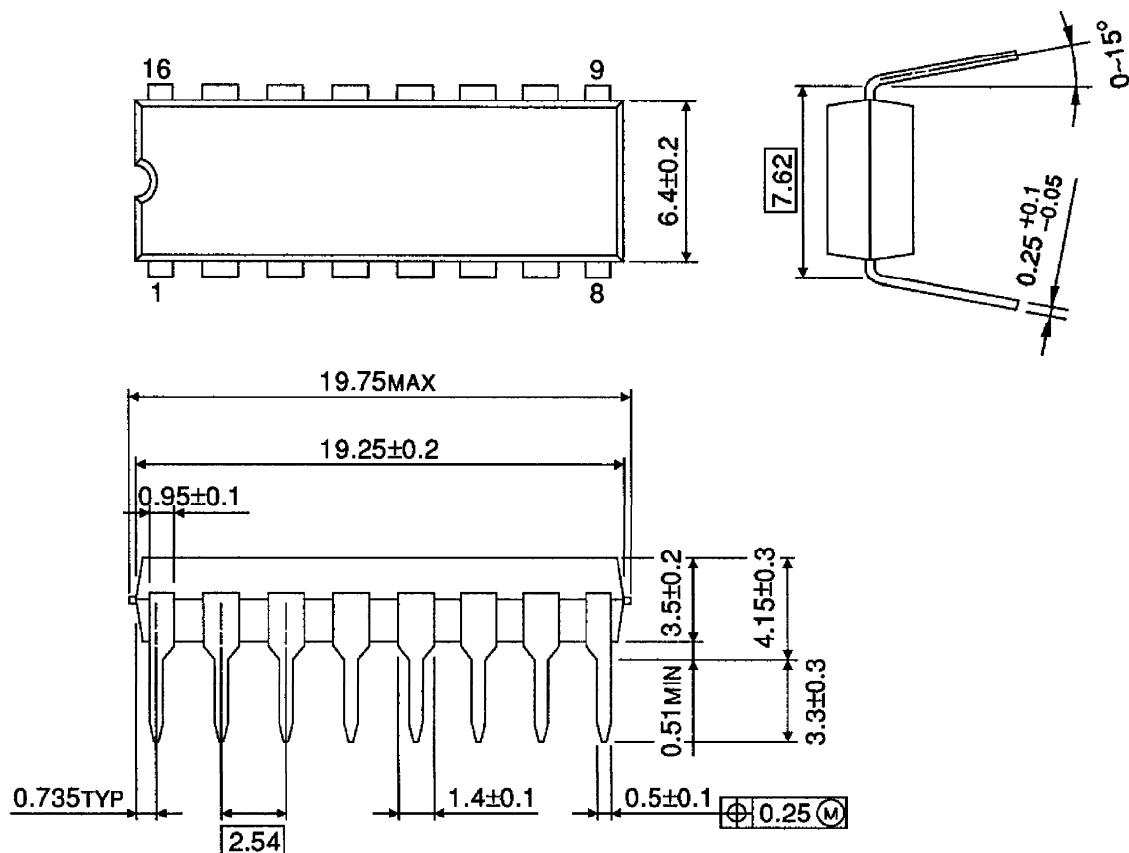
Utmost care is necessary in the design of the output line, COMMON and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.



OUTLINE DRAWING

DIP16-P-300-2.54A

Unit : mm

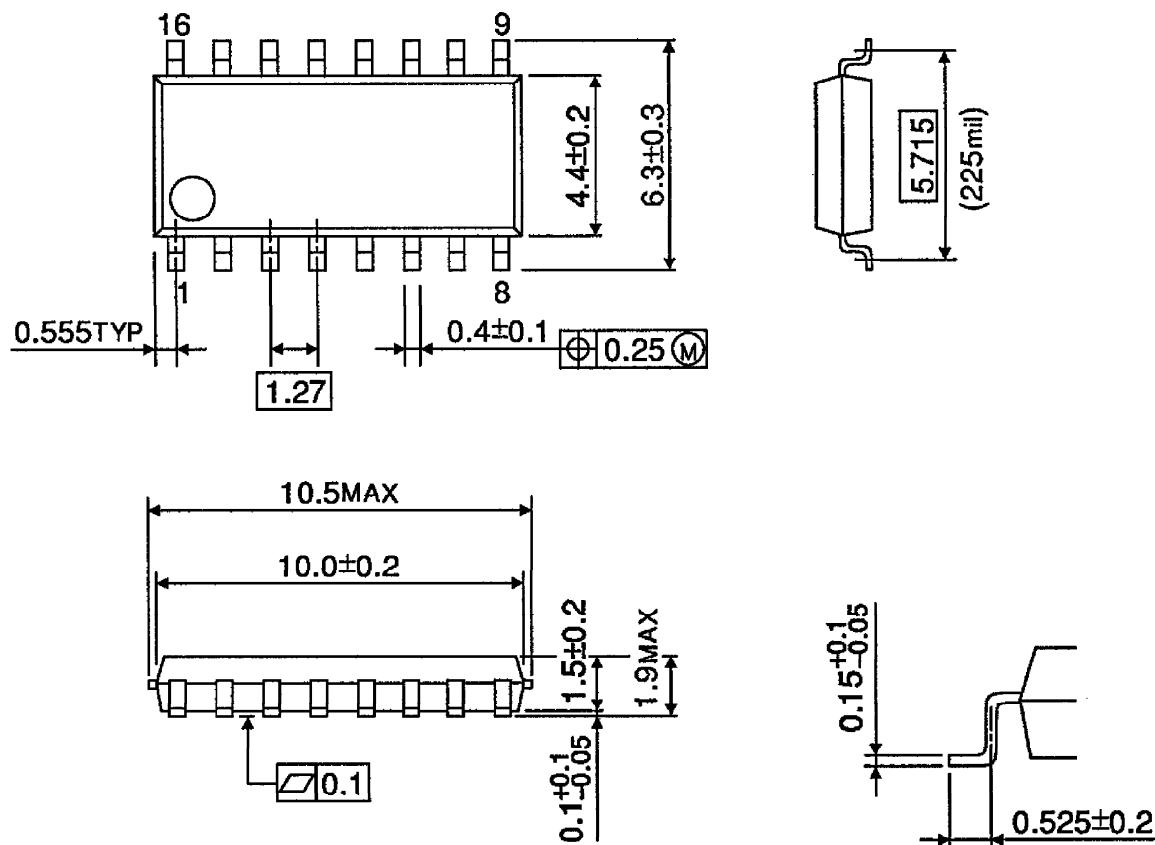


Weight : 1.11g (Typ.)

OUTLINE DRAWING

SOP16-P-225-1.27

Unit : mm



Weight : 0.16g (Typ.)